

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	50091	wiring near4 electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:08
L2	2496	(wiring near4 electrode) and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:13
L3	1761	(wiring near4 electrode) and rigid\$4 and plate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
L4	60	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
L5	36	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder) and terminal	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
L6	9	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder) and terminal and (semiconductor near4 element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:15

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S1	0	("6064114" "6617655" "6797544".PN. and (semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal\$4) and mount	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:10
S2	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal\$4) and mount	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:11
S3	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:26
S4	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:12
S5	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13
S6	9	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13
S7	9	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13

## EAST Search History

S8	1	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and ((cut\$4 or dic\$4) near8 plate) and viscosity and liquid and (heat\$4 or thermal\$4 or anneal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:36
S9	1	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4) and viscosity and liquid and (heat\$4 or thermal\$4 or anneal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:37
S10	2	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:38
S11	10	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:41
S12	39	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and "CMP" and (cut\$4 or dic\$4) and rigidity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:08